



Request for Quote and Specifications of Automatic Wafer cutting/dicing machine for up to 8” substrates

- The GEECI (Gallium Nitride Ecosystem Enabling Centre and Incubator) at SID-Indian Institute of Science is seeking bids from qualified industries for an automatic wafer cutting and dicing tool as per the specifications below.
- Companies need to submit two bids, a technical bid and a commercial bid, in **two separate** sealed envelopes. The bids should be submitted no later than 30 days from the date of posting of this tender, as listed on the website date/time stamp, and by 5 pm on the 30th day or next weekday in case the 30th day falls on a weekend or a national holiday.
- Both technical and commercial bids should be addressed to “The Chief Executive, SID, IISc, Bangalore 560012, GST # 29AAATS5333E1ZJ.”
- All quotations should be CIF Bangalore.
- Cost of last mile transportation, including any insurance, from port of shipment to IISc has to be quoted as an option.
- In case of courier shipments maximum permissible weight would be 70kgs.
- The envelopes should be addressed to “Prof. Srinivasan Raghavan, CeNSE, IISc, Bangalore, 560012” and submitted to the office at CeNSE, IISc in Room No. GF 15 between 9 am and 5 pm.
- All questions regarding this tender should be addressed to Prof. Srinivasan Raghavan at the email address sraghavan@iisc.ac.in
- Post such submission all vendors should send an email to sraghavan@iisc.ac.in with the subject line: “GEECI_Bidder’s name_Tool Name” to intimate him of the submission within one day.
- Deviations from the technical specifications requested are allowed. Such deviations must be highlighted and justified. Their acceptance or rejection will be left to the discretion of the technical committee.
- The equipment sought will be placed at the Centre for Nano Science and Engineering (CeNSE), Indian Institute of Science (IISc). IISc is India’s No. 1 institution on higher learning and the Center for Nano Science and Engineering is home to one of the best academic fabs in the world.
- The technical response, corresponding to the tool being offered, should be in the form of a compliance table with at least 5 columns. Serial number in column 1. Each of the numbered technical items below should be addressed in a separate row of the table in column 2. Compliance to this requirement, in Yes/No, deviation from it and justification should be provided in the neighboring columns 3-5. Post the opening of a hard copy of the technical bid the committee will request for a soft copy of the files for further processing. Companies should **NOT** mail soft copies of the files unless specifically requested for.
- Detailed technical specifications of the tool being offered should be included.
- Any additional capabilities or technical details, that you would like to bring to the attention of the purchase committee, can be listed at the end of the technical table.
- If multiple systems can fulfill the requirements, vendors can submit multiple bids.
- Vendors are encouraged to highlight the advantages of their tools over comparable tools from the competitors.
- The commercial bid should be broken up to the maximum extent possible into separate items with a cost against each to enable better comparison of price for various configurations across the bidders. As an option, please provide itemized cost for any *suggested* accessories/add-ons that may enhance the usability, capability, accuracy or reliability of the tool. Vendors are

Technical requirements:

	Description	Specifications
1.	Major Application	Dicing of wafers, materials such as Silicon carbide, Sapphire, Pyrex glass, Alumina, Silicon, bonded wafers of Silicon and glass etc
2.	Part accommodation	Wafer size up to 8 inch circular, Square 250mm, irregular shapes, thickness 0.2 to 2.0 mm or higher. In case of different models for 6" and 8" wafers vendor is encouraged to submit two different quotes.
3.	Spindle Power	2.2 kW or better
4.	Max Spindle revolution range	6000- 60000 RPM or better
5.	Spindle rated torque	0.28 N-m or better
6.	Dicing modes	Machine to have both ultrasonic and normal dicing capability
7.	Operation	Min 10" LCD touch panel
8.	Axes guideways X,Y,Z	Linear motion guideways with ball screw mechanism
9.	Axes Travel X, Y	260, 260 mm
10.	Position accuracy	0.002 mm
11.	Repeatability and accuracy of Z Axis	+/-0.001mm or better, Max stroke 32mm
12.	X axis feed rate	0.1 - 500 mm/s
13.	Moving Resolution Z Axis	0.00005 mm
14.	Θ Axis	Rotating angle 360 ⁰
15.	Θ Axis accuracy	0.4 min
16.	Pattern recognition system	Yes
17.	Software	System should come with state-of-the-art equipment operation software, latest OS & Monitor for managing the system.
18.	Other components	Security features protecting the integrity of the system and electronics in case of power failure & component failure .
19.	Additional optional equipment	Additional allied equipment for efficient working of the machine such as, Chiller, water recirculation system, wafer taping, de-taping (UV curing), mist collector etc are to be quoted separately.
20.		Please include options currently available that can be added on in the future.
	Common Terms and Conditions: A separate table to be included for each of the items below in the technical bid.	
21.	SEMI Standards: The technical bid should include details of the SEMI standards the tool confirms to.	
22.	Clean Room compatibility: Vendor should indicate if the tool is compatible with a class 100 to class 1000 clean room.	
23.	Shipping: On all systems the cost of shipping up to IISc should be included. IISc will help with customs clearance at Bangalore Airport. Please include your payment option. IISc would prefer to retain at least 20% of payment till instruments have been	

	commissioned and successfully demonstrated.
24.	Tool Qualification and Acceptance: Commissioning shall involve demonstration of dicing on 4-6 inch SiC, Si both blank and coated with up to 5 microns of GaN as negotiated and included in the purchase order. <u>Details of the stage wise certification protocols to be pursued for tool acceptance should be included in the technical bid.</u> <u>The PO will include a mutually agreed upon set of tool qualification criteria.</u> Please list a set of acceptance tests for on-site (vendor) inspection and after installation at IISc.
25.	Tool Training: The bid should include as an option the cost of training personnel on site before shipment and on site post installation.
26.	Tool footprint and utilities: A floor plan should be part of the technical bid. A list of utility requirements should be part of the technical bid. The system should be compatible with 240±10V, 50 Hz single phase or 415±20V, 50 Hz 3 phase supplies. The MINIMUM set of utility requirements needed are provided in Table 1. If there are additional utility requirements please include them in the technical bid. Please list connector types for all utilities.
27.	Cost of Ownership and supply of spares: The quote should include a listing of spares that need to be replaced periodically to ensure that the system is in operation in a stable fashion – the stability parameters being defined by the vendor and agreed to by the client – the cost of such items, the ability to guarantee their availability at this cost for a period of 5 years from the time of procurement. The aim of this exercise is to compare cost of ownerships between reactors. Commercial bid should include the cost of such spares.
28.	Maintenance: The cost of an annual maintenance contract and cost of emergency technical support that may involve an engineer being on site should be quoted for in the commercial bid and addressed in the technical bid. The availability of trained engineers in India for servicing the system will be preferred and should be described in the technical bid.
29.	Maintenance: On all systems a set of basic tools required -non-standard screw or spanner head that is required for routine tool maintenance should be mentioned- for performing routine maintenance should be included.
30.	Maintenance: System operation, process and troubleshooting manuals and detailed drawings are a must. Their inclusion must be indicated in the technical bid.
31.	Online support: System should have the capability for online diagnostics from a remote location in case of tool problems.
32.	Post sales service and Indian Presence: Bidders should provide details of after sales service and support available in India. If not India, the nearest geographical location should be specified. Please provide details of the number of trained personnel in India who can service the machine, the number of tools sold in India and the corresponding number in the southern region or in Bangalore.
33.	Shipping: On all systems the cost of shipping up to IISc should be included. IISc will help with customs clearance at Bangalore Airport.
34.	Payment Terms and Conditions: On all systems the payment terms should be specified in the technical and commercial proposal and is subject to negotiation. Please include your payment option. IISc would prefer to retain at least 20% of payment till instruments have been commissioned and successfully demonstrated.
35.	References: Bidders should provide details of other locations in India with similar tool installations.

36.	References: Bidders should provide details of at least 3 other locations globally where similar tool installations have been deployed for device fabrication in a clean room preferably for production purposes.
37.	Company financials: Bidder shall have to submit audited accounts of financial year 2017-18, 2018-19 and 2019-20. Audited statement must be signed and stamped by qualified chartered accounted. Income Tax return for assessment year – 2017-18, 2018-19 and 2019-20.
38.	The following documentation should be provided. ISO9001 quality certification. CE marking confirmation.
39.	III-V nitride processing: Please include information on whether the tool and its fixturing has been used for dicing of on GaN on Si and SiC wafers and the parameters for such dicing can be provided by the vendor.

